



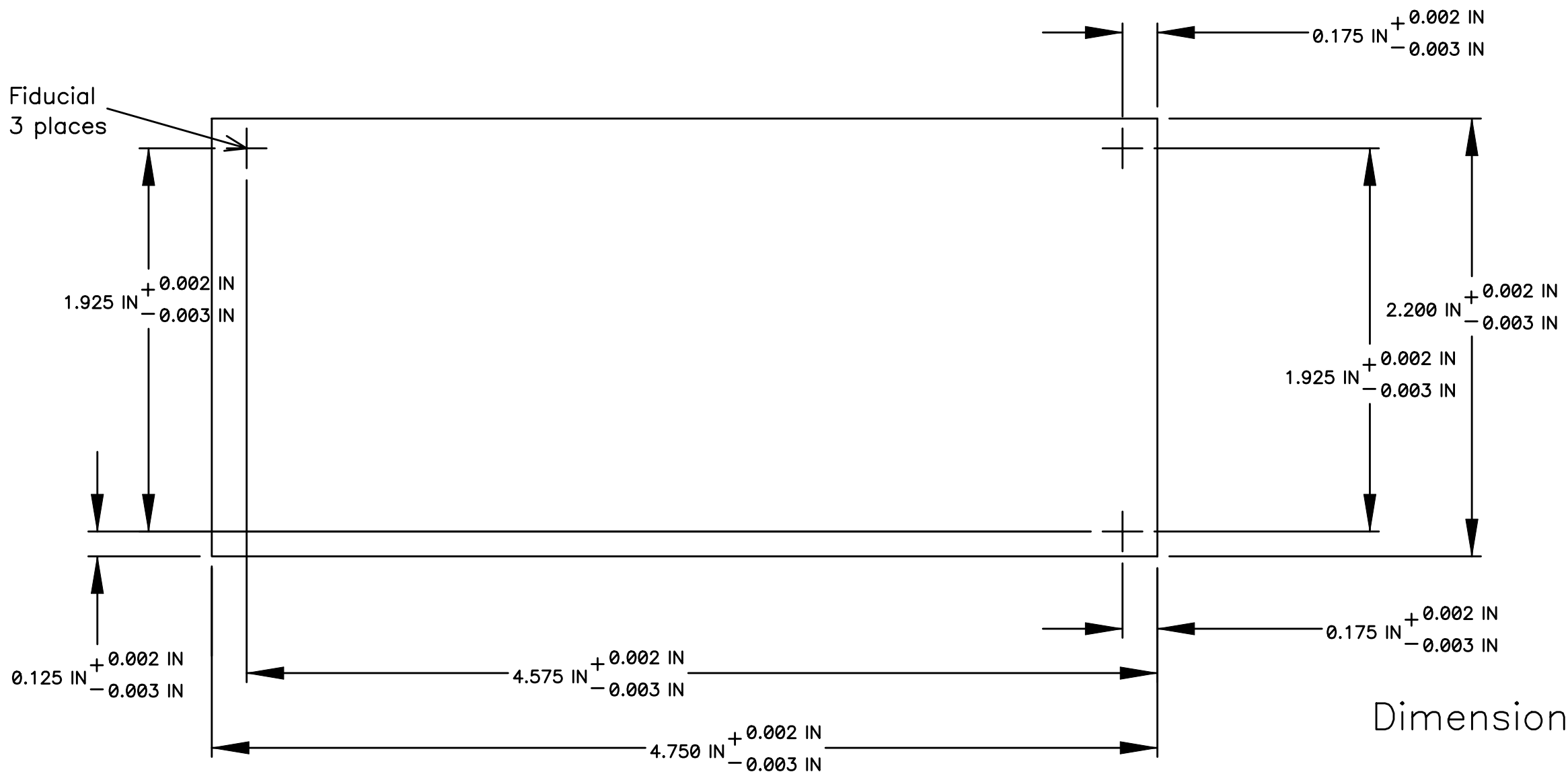
BOARD LAYERING PLAN

2	4	5	Comps.
12mil, multi-functional grade FR-408 prepreg			TOP
10mil, 1oz. over 1oz. double-clad, multi-functional grade FR-4 rigid laminate			Gnd
8mil, multi-functional grade FR-4 prepreg (may adjust thickness to achieve overall board thickness)			Vcc
3	8		Gnd
10mil, 1oz. over 1oz. double-clad, multi-functional grade FR-4 rigid laminate			Vdd
12mil, multi-functional grade FR-408 prepreg			Comps.
Surface copper thickness, both sides, 1-1/2oz.			

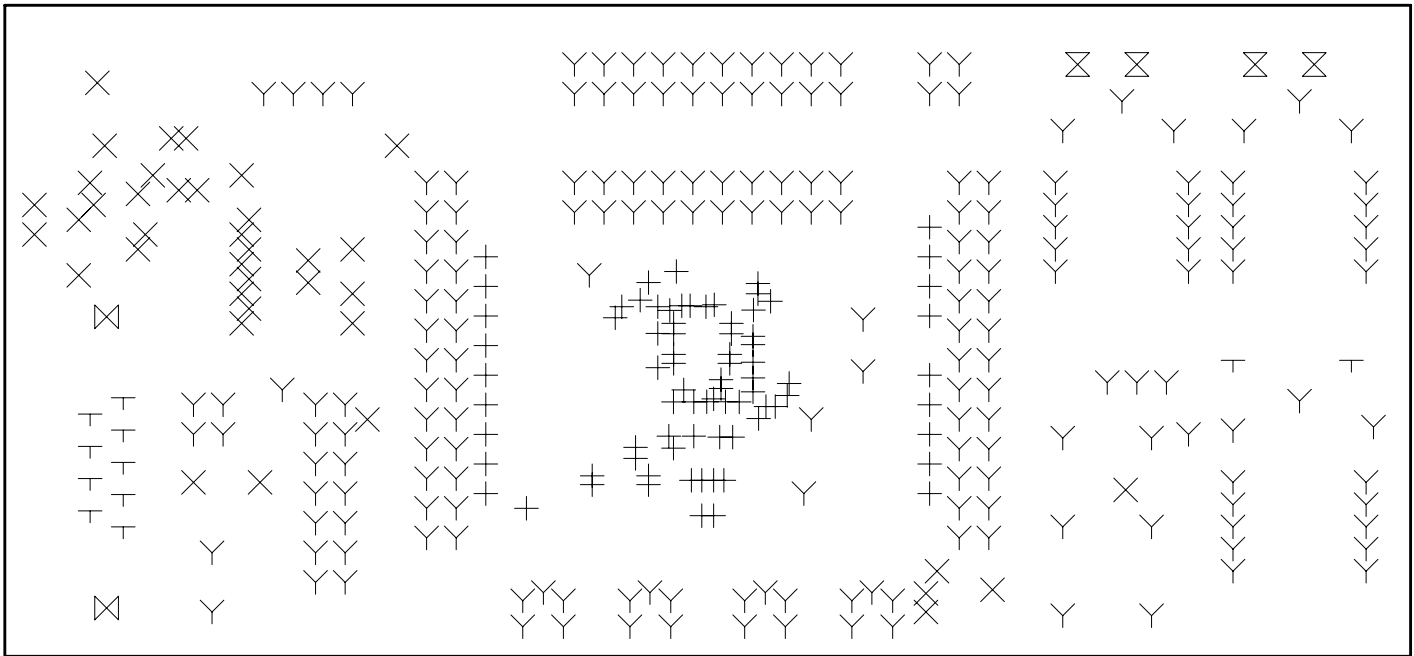
- NOTES:
- 1. Layering and materials shall be as described above. Note especially the dielectric materials.
 - 2. Surface copper layers shall be 1-1/2 ounce nom. finished thickness except as noted above.
 - 3. Finished board thickness shall be 62mils, +/-3 mils, 65mils abs. max.
 - 4. All exposed copper shall be hot-air-levelled solder plated (60/40 tin-lead, 1 to 2 mils) and be flat and free of excess solder.
 - 5. Solder mask and silk screen both sides shall be vendor's standard.
 - 6. Board acceptability after baking shall be per IPC-A-600, Class II.
 - 7. Board twist and warp shall not exceed 4mils/linear inch.
 - 8. Center-most prepreg layer thickness may be adjusted to give overall board thickness limits.

Notes

Title LMH0030 Eval Board		
Size A	Number SD130ASM-PCB	Rev G
Date 13 July 06		Drawn by Gary Melchior
Filename sd130asm_revG.sch		Sheet 1 of 13



Title LMH0030 Eval Board		
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Drill

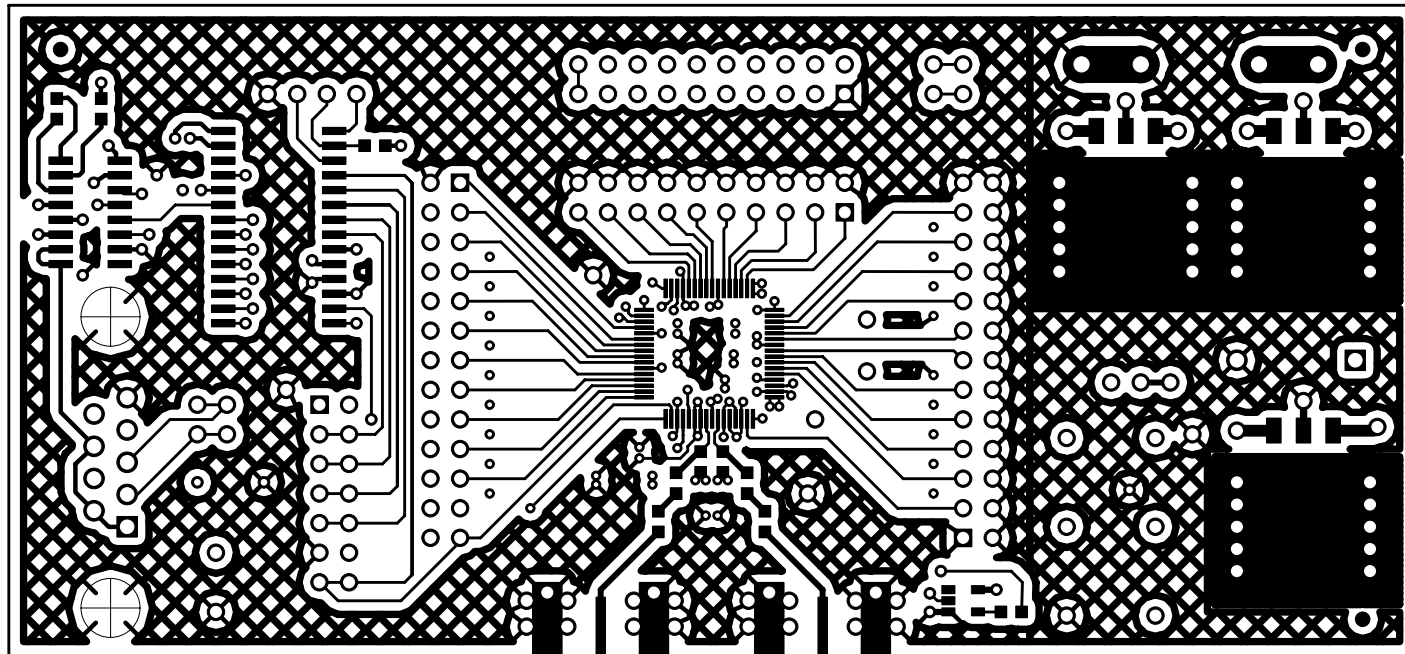
Drill Symbol Table		
Hole Dia (inch)	Symbol	Quantity
0.013	+	80
0.020	X	39
0.038	Y	195
0.046	T	11
0.052	X	4
0.124	X	2

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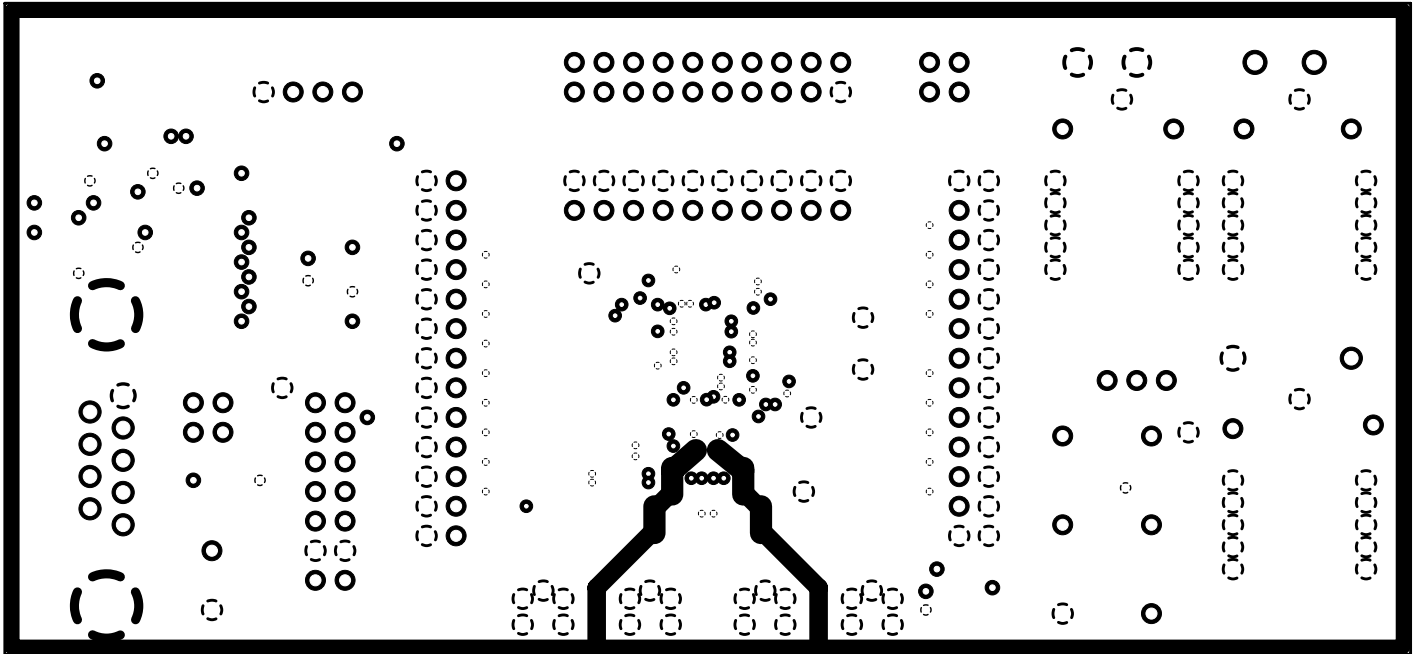
National
Semiconductor

Interface Products



Top

Title LMH0030 Eval Board			
Size A	Number SD130ASM-PCB		Rev G
Date 13 July 06	Drawn by Gary Melchior		
Filename sd130asm_revG.dwg	Sheet 4	of 13	



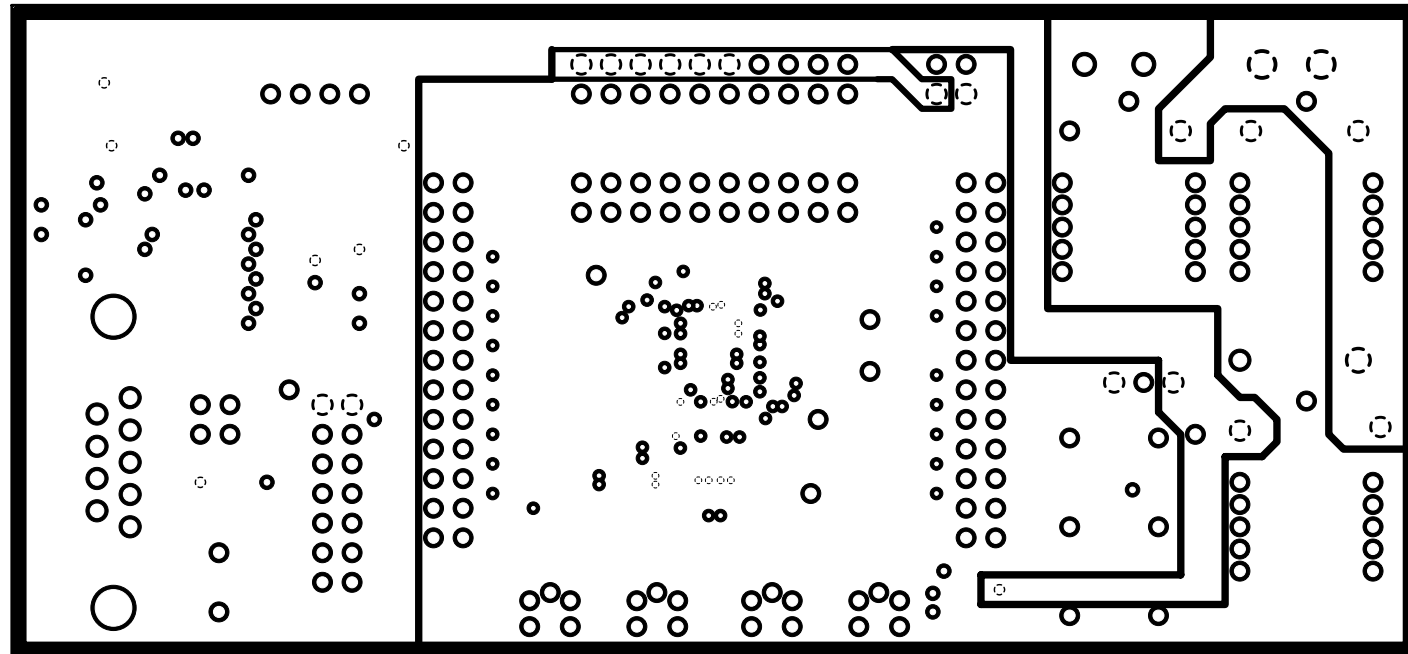
Top Ground

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Semiconductor

Interface Products



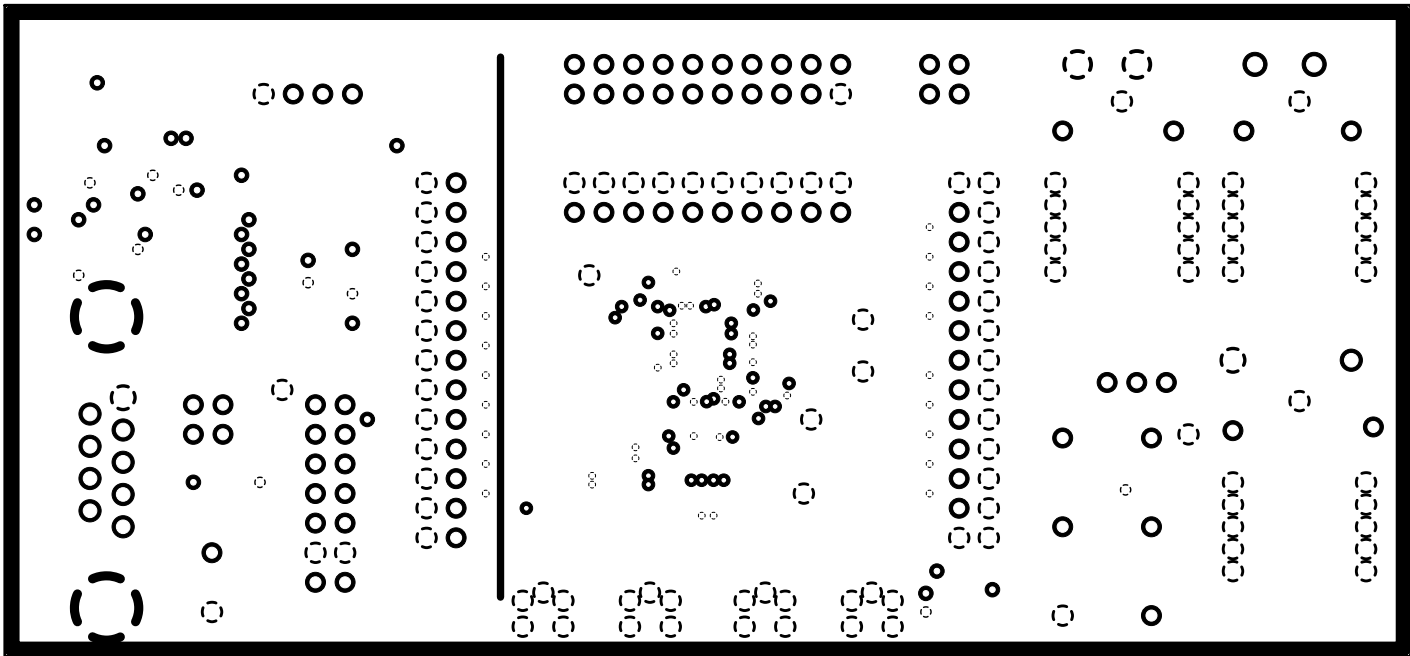
Vcc Plane

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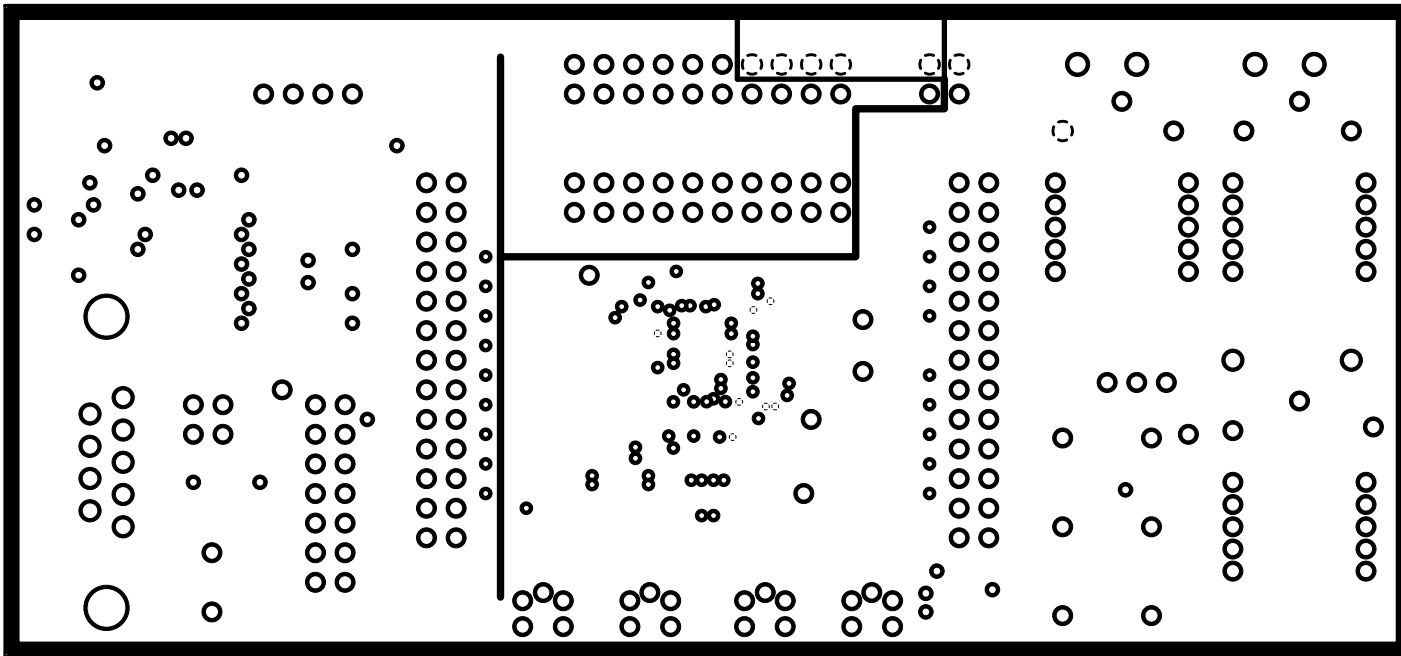
National
Semiconductor

Interface Products



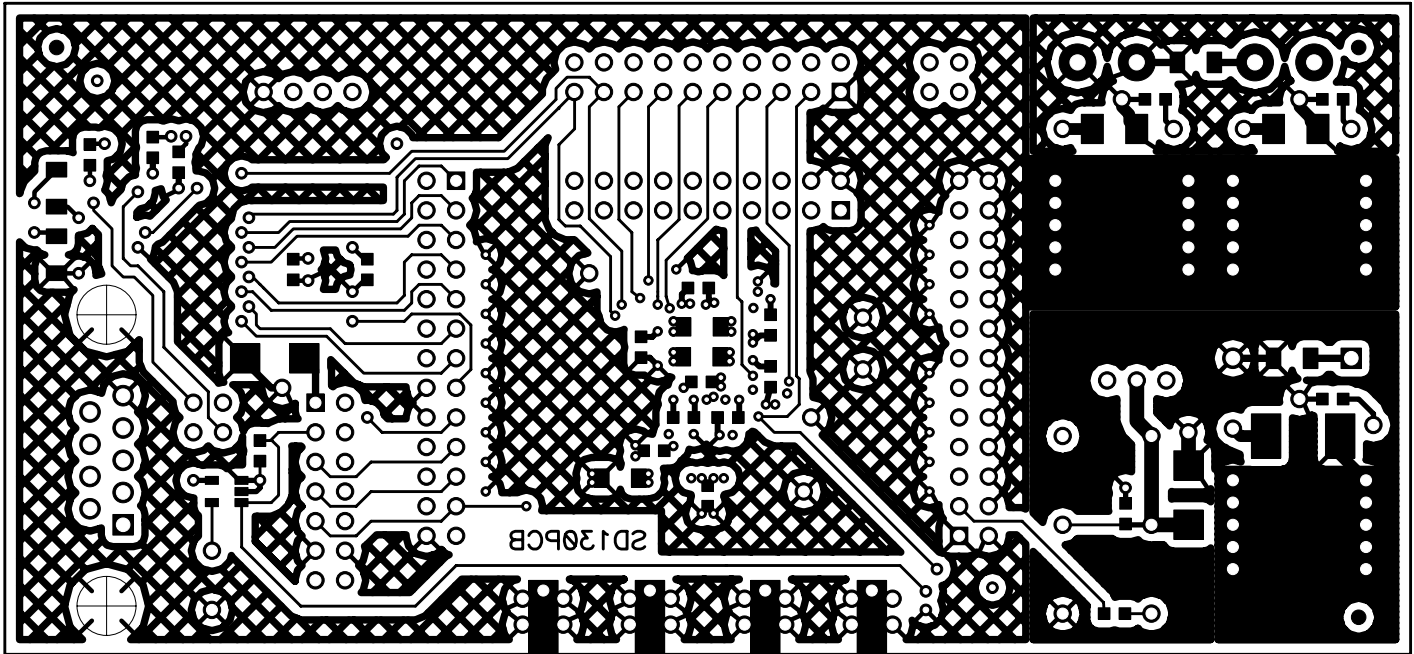
Gnd Plane

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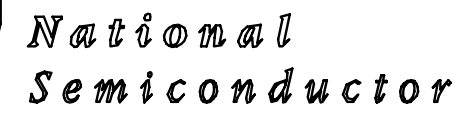
Vdd 2.5V Plane

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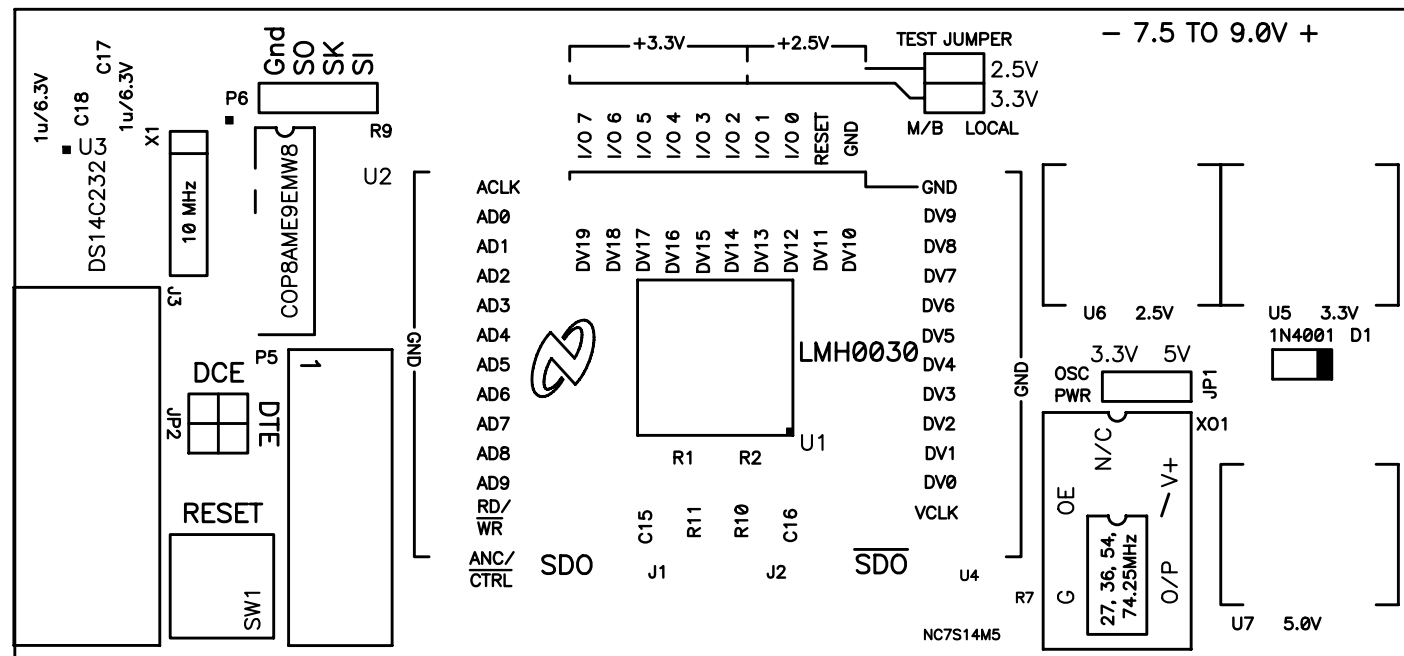


Bottom

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Size A	Number SD130ASM-PCB		Rev G
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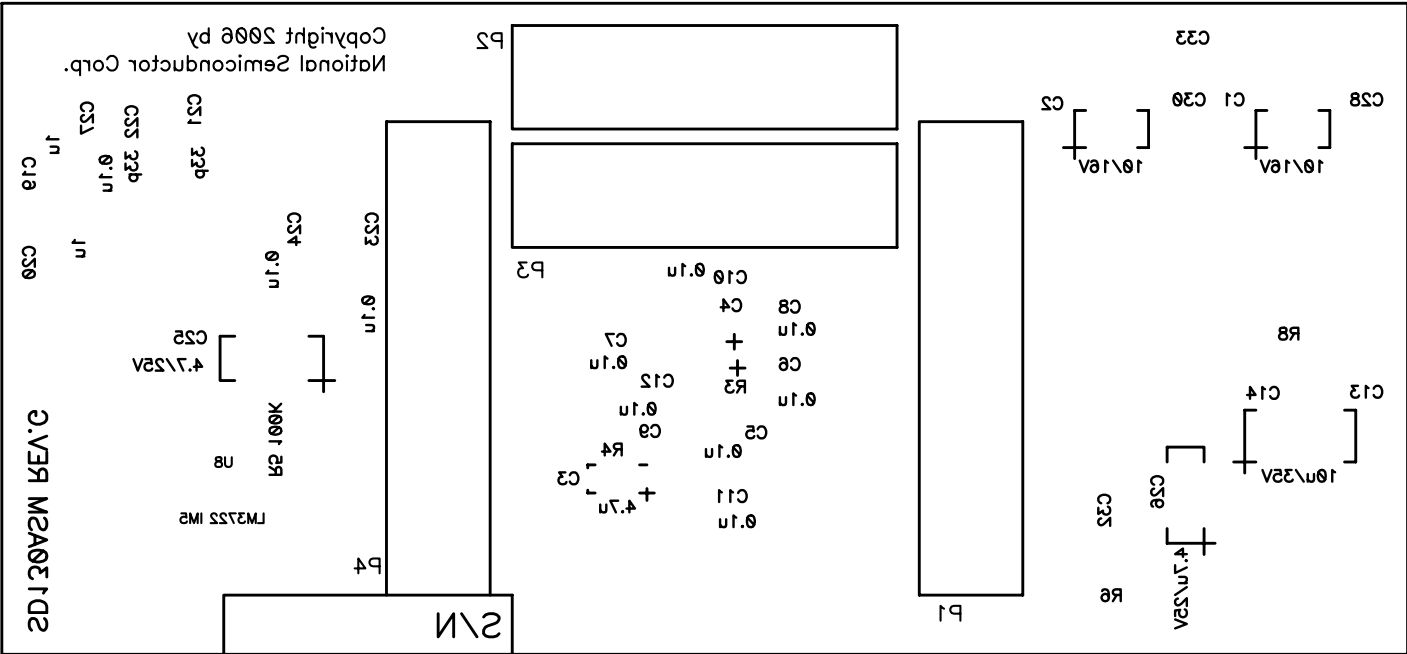


Interface Products



Top Silk Screen

Title			LMH0030 Eval Board		
Size		Number		Rev	
A		SD130ASM-PCB		G	
Date			Drawn by		
13 July 06			Gary Melchior		
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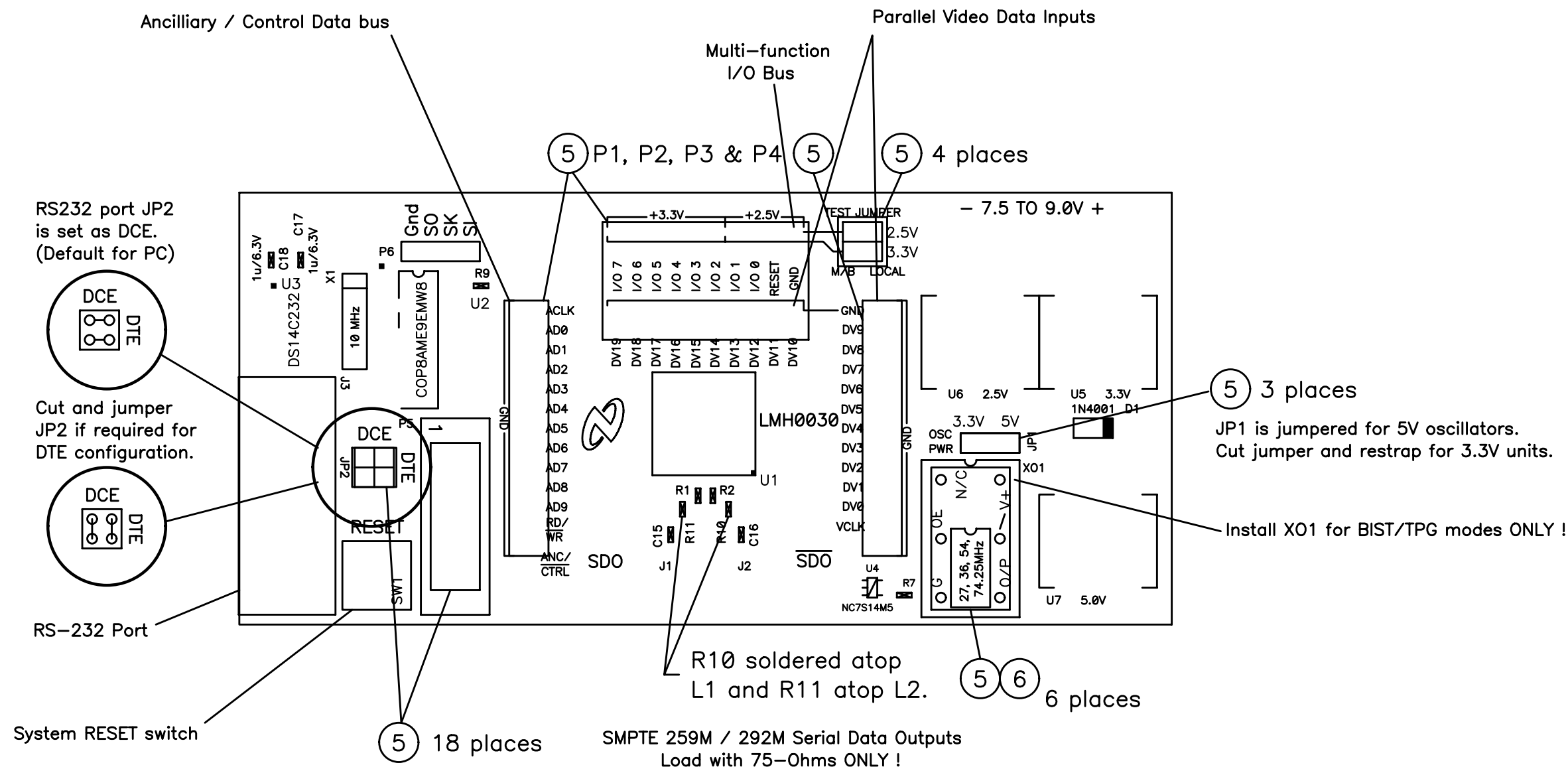
Bottom Silk Screen

Title LMH0030 Eval Board			
Size A	Number SD130ASM-PCB		Rev G
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Interface Products

Top Assembly

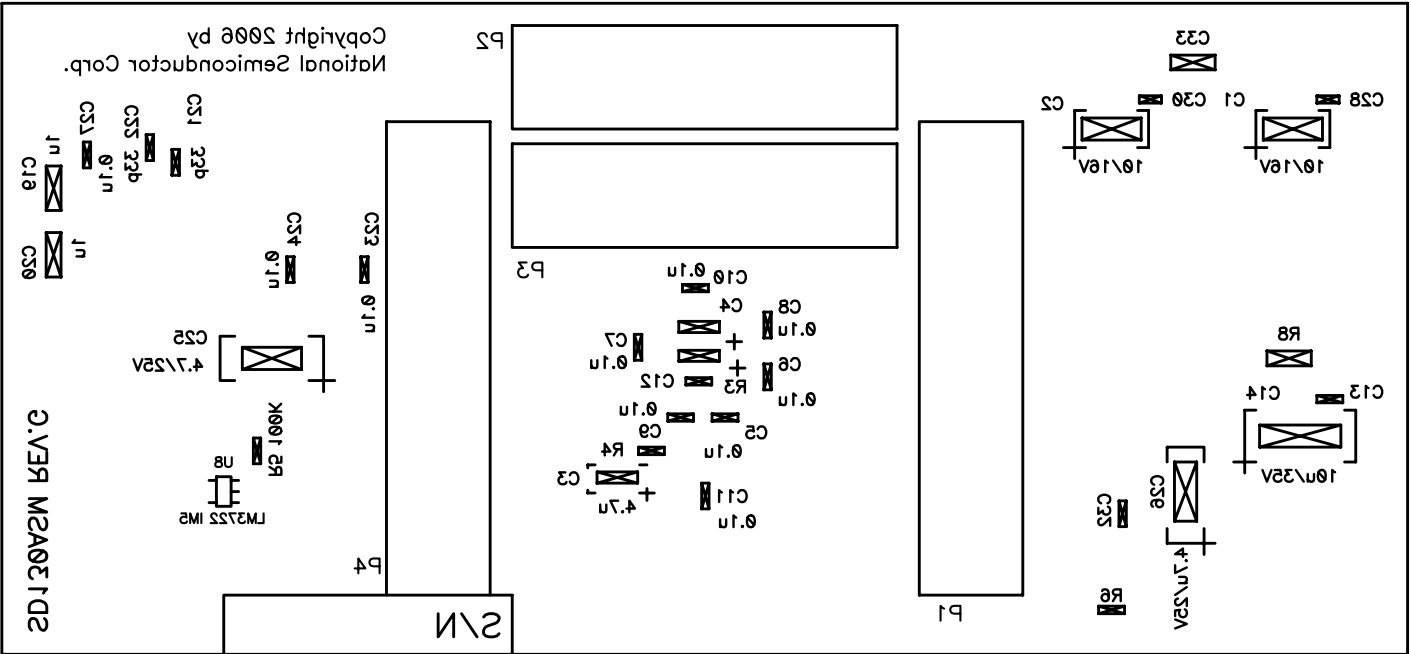


6. Socket pins in 6 places at X01(optional).
- 5. Holes shall be free of solder.
4. No substitutions.
3. Not used on Rev. F assembly.
2. Alternate component type.
- NOTES: 1. Optional component. See special assembly instructions.

Top Silk Screen

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Bottom Assembly



Bottom Silk Screen

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